

# 2N3906

Preferred Device

## General Purpose Transistors

PNP Silicon

### Features

- Pb-Free Packages are Available\*

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	$V_{CEO}$	40	Vdc
Collector – Base Voltage	$V_{CBO}$	40	Vdc
Emitter – Base Voltage	$V_{EBO}$	5.0	Vdc
Collector Current – Continuous	$I_C$	200	mA <sub>dc</sub>
Total Device Dissipation @ $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	625 5.0	mW mW/ $^\circ\text{C}$
Total Power Dissipation @ $T_A = 60^\circ\text{C}$	$P_D$	250	mW
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	1.5 12	W mW/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

### THERMAL CHARACTERISTICS (Note 1)

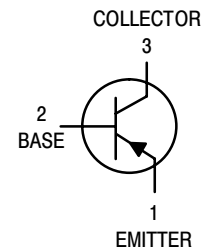
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	$^\circ\text{C}/\text{W}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

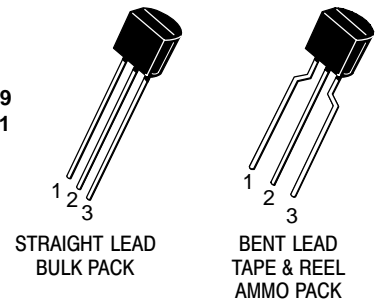
1. Indicates Data in addition to JEDEC Requirements.



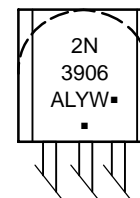
ON Semiconductor®



TO-92  
CASE 29  
STYLE 1



### MARKING DIAGRAM



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## 2N3906

### ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
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#### OFF CHARACTERISTICS

Collector – Emitter Breakdown Voltage (Note 2)	$(I_C = 1.0 \text{ mAdc}, I_B = 0)$	$V_{(BR)CEO}$	40	–	Vdc
Collector – Base Breakdown Voltage	$(I_C = 10 \text{ }\mu\text{Adc}, I_E = 0)$	$V_{(BR)CBO}$	40	–	Vdc
Emitter – Base Breakdown Voltage	$(I_E = 10 \text{ }\mu\text{Adc}, I_C = 0)$	$V_{(BR)EBO}$	5.0	–	Vdc
Base Cutoff Current	$(V_{CE} = 30 \text{ Vdc}, V_{EB} = 3.0 \text{ Vdc})$	$I_{BL}$	–	50	nAdc
Collector Cutoff Current	$(V_{CE} = 30 \text{ Vdc}, V_{EB} = 3.0 \text{ Vdc})$	$I_{CEX}$	–	50	nAdc

#### ON CHARACTERISTICS (Note 2)

DC Current Gain	$(I_C = 0.1 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$	$h_{FE}$	60	–	–	
	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$		80	–	–	
	$(I_C = 10 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$		100	300	–	–
	$(I_C = 50 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$		60	–	–	–
	$(I_C = 100 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc})$		30	–	–	–
Collector – Emitter Saturation Voltage	$(I_C = 10 \text{ mAdc}, I_B = 1.0 \text{ mAdc})$ $(I_C = 50 \text{ mAdc}, I_B = 5.0 \text{ mAdc})$	$V_{CE(sat)}$	–	0.25 0.4	Vdc	
Base – Emitter Saturation Voltage	$(I_C = 10 \text{ mAdc}, I_B = 1.0 \text{ mAdc})$ $(I_C = 50 \text{ mAdc}, I_B = 5.0 \text{ mAdc})$	$V_{BE(sat)}$	0.65 –	0.85 0.95	Vdc	

#### SMALL-SIGNAL CHARACTERISTICS

Current – Gain – Bandwidth Product	$(I_C = 10 \text{ mAdc}, V_{CE} = 20 \text{ Vdc}, f = 100 \text{ MHz})$	$f_T$	250	–	MHz
Output Capacitance	$(V_{CB} = 5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz})$	$C_{obo}$	–	4.5	pF
Input Capacitance	$(V_{EB} = 0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$	$C_{ibo}$	–	10	pF
Input Impedance	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	$h_{ie}$	2.0	12	$k\Omega$
Voltage Feedback Ratio	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	$h_{re}$	0.1	10	$\times 10^{-4}$
Small-Signal Current Gain	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	$h_{fe}$	100	400	–
Output Admittance	$(I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	$h_{oe}$	3.0	60	$\mu\text{mhos}$
Noise Figure	$(I_C = 100 \text{ }\mu\text{Adc}, V_{CE} = 5.0 \text{ Vdc}, R_S = 1.0 \text{ k}\Omega, f = 1.0 \text{ kHz})$	NF	–	4.0	dB

#### SWITCHING CHARACTERISTICS

Delay Time	$(V_{CC} = 3.0 \text{ Vdc}, V_{BE} = 0.5 \text{ Vdc}, I_C = 10 \text{ mAdc}, I_{B1} = 1.0 \text{ mAdc})$	$t_d$	–	35	ns
Rise Time		$t_r$	–	35	ns
Storage Time	$(V_{CC} = 3.0 \text{ Vdc}, I_C = 10 \text{ mAdc}, I_{B1} = I_{B2} = 1.0 \text{ mAdc})$	$t_s$	–	225	ns
Fall Time	$(V_{CC} = 3.0 \text{ Vdc}, I_C = 10 \text{ mAdc}, I_{B1} = I_{B2} = 1.0 \text{ mAdc})$	$t_f$	–	75	ns

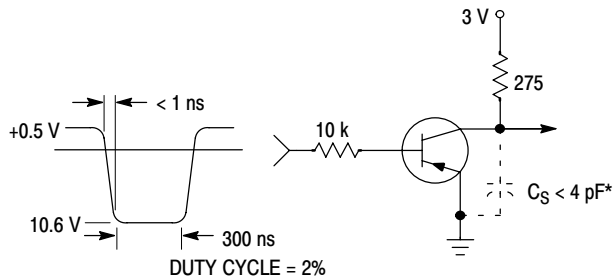
2. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ ; Duty Cycle  $\leq 2\%$ .

# 2N3906

## ORDERING INFORMATION

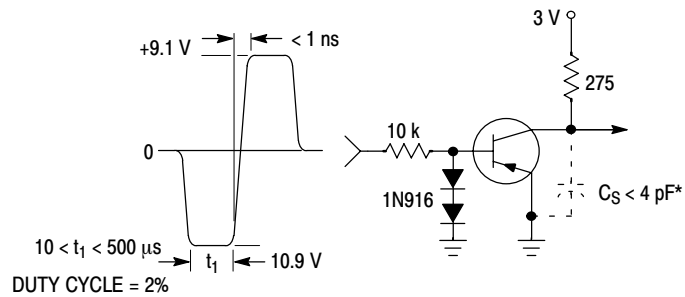
Device	Package	Shipping†
2N3906	TO-92	5000 Units / Bulk
2N3906G	TO-92 (Pb-Free)	5000 Units / Bulk
2N3906RL1	TO-92	5000 Units / Bulk
2N3906RL1G	TO-92 (Pb-Free)	5000 Units / Bulk
2N3906RLRA	TO-92	2000 / Tape & Reel
2N3906RLRAG	TO-92 (Pb-Free)	2000 / Tape & Reel
2N3906RLRM	TO-92	2000 / Ammo Pack
2N3906RLRMG	TO-92 (Pb-Free)	2000 / Ammo Pack
2N3906RLRP	TO-92	2000 / Tape & Reel
2N3906RLRPG	TO-92 (Pb-Free)	2000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



\* Total shunt capacitance of test jig and connectors

**Figure 1. Delay and Rise Time Equivalent Test Circuit**



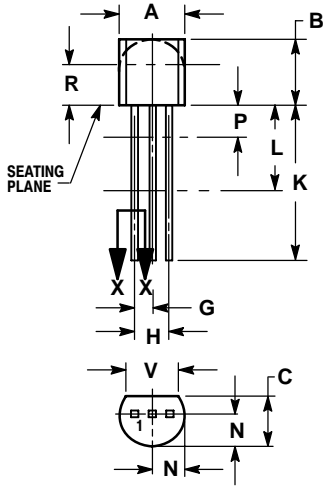
\* Total shunt capacitance of test jig and connectors

**Figure 2. Storage and Fall Time Equivalent Test Circuit**

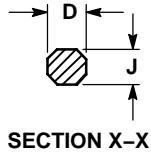
# 2N3906

## PACKAGE DIMENSIONS

TO-92 (TO-226)  
CASE 29-11  
ISSUE AM



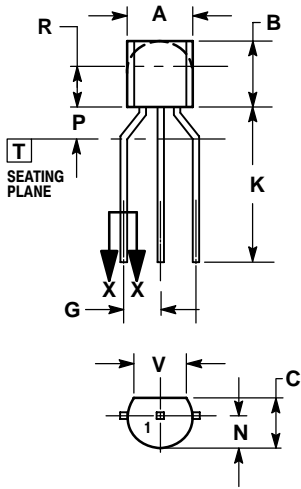
STRAIGHT LEAD  
BULK PACK



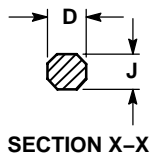
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.175	0.205	4.45	5.20
B	0.170	0.210	4.32	5.33
C	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
H	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500	---	12.70	---
L	0.250	---	6.35	---
N	0.080	0.105	2.04	2.66
P	---	0.100	---	2.54
R	0.115	---	2.93	---
V	0.135	---	3.43	---



BENT LEAD  
TAPE & REEL  
AMMO PACK



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

DIM	MILLIMETERS	
	MIN	MAX
A	4.45	5.20
B	4.32	5.33
C	3.18	4.19
D	0.40	0.54
G	2.40	2.80
J	0.39	0.50
K	12.70	---
N	2.04	2.66
P	1.50	4.00
R	2.93	---
V	3.43	---

STYLE 1:

1. EMITTER
2. BASE
3. COLLECTOR